

MATERIAL DECLARATION SHEET

Material Number	TBU-CA Series			
Product Line	TBU Products			
Compliance Date	1/1/2010			
RoHS Compliant	Yes	MSL	1	

No.	Construction Element (subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1.	Encapsulation	Epoxy resin	0.032629	Silica fused	60676-86-0	90.45	37.429	41.38
				Epoxy resin	Trade Secret	6	2.482	
				Phenol resin	Trade Secret	3	1.241	
				Carbon black	1333-86-4	0.55	0.228	
2	Lead Frame	Copper Alloy	0.038388	Copper	7440-50-8	96	46.568	48.69
				Iron	7439-89-6	2.2	1.061	
				Phosphorus	7723-14-0	0.075	0.015	
				Zinc	7440-66-6	0.1	0.063	
				Silver (plating)	7740-22-4	1.624	0.979	
				Lead (impurity)	7439-92-1	0.001	0.005	
3	Chip	Silicon	0.003941	Silicon	7440-21-3	100	5.000	5.00
4	Die-attach	Silver epoxy	0.001296	Epoxy resin	Trade secret	5.5	0.0902	1.64
				Functionalized ester	Trade secret	0.55	0.00902	
				Polymeric compound	Trade secret	0.55	0.00902	
				Silver	7440-22-4	93.4	1.53176	
5	Bond wire	Gold	0.000188	Gold	7440-57-5	99.9	0.23976	0.24
				Potential impurities may include Ag, Be or Ca ≤ 30 ppm	7440-22-4; 7440-41-7; 7440-70-2	0.01	0.00024	
6	Terminal Finish	Matte Tin	0.002407	Tin	7440-31-5	100	3.05	3.05
		Total weight	0.078849					

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This Document was updated on: 29-Jan-2019

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.